

Experiences with Aging Simulation

Christian Maier, Robert Bosch GmbH

Experiences with Aging Simulation

Motivation

- ▶ Devices in state-of-the-art semiconductor processes can be operated in regions where degradation may happen
 - ▶ Aging simulation needed to take the effect of device degradation during design into account
 - ▶ Aging models needed for relevant degradation mechanisms
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- ▶ At Bosch, process design kits (PDKs) from different vendors are used
 - ▶ Aging simulation not supported in every PDK

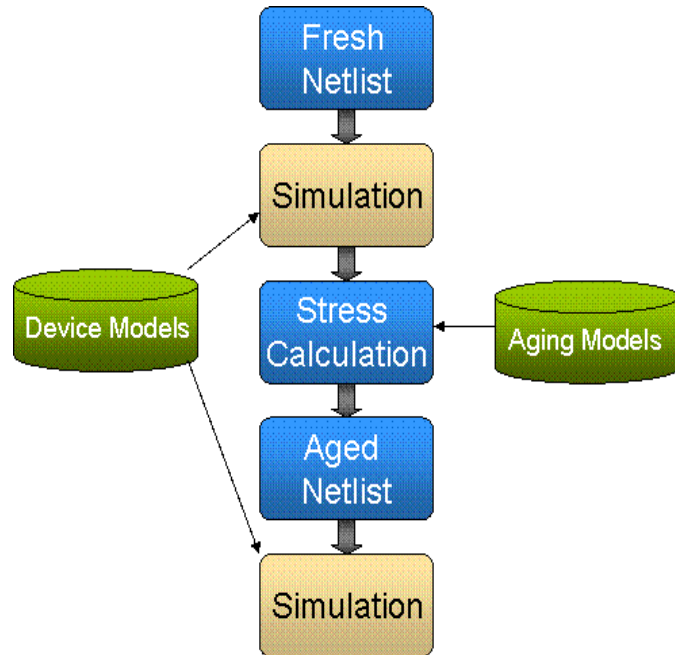
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History

- ▶ Main Activities of Bosch regarding reliability simulation within funded projects:
- ▶ Project ELIAS (2007..2010): RelXpert URI improved for support of subcircuit device models (Cadence has been project partner) → Implementation into Cadence 5.1.41
- ▶ Project RESIST (2014...2017): Improvement of reliability simulation flow to support (i.e. enhance) process design kits from different vendors

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Aging Simulation Flow with RelXpert

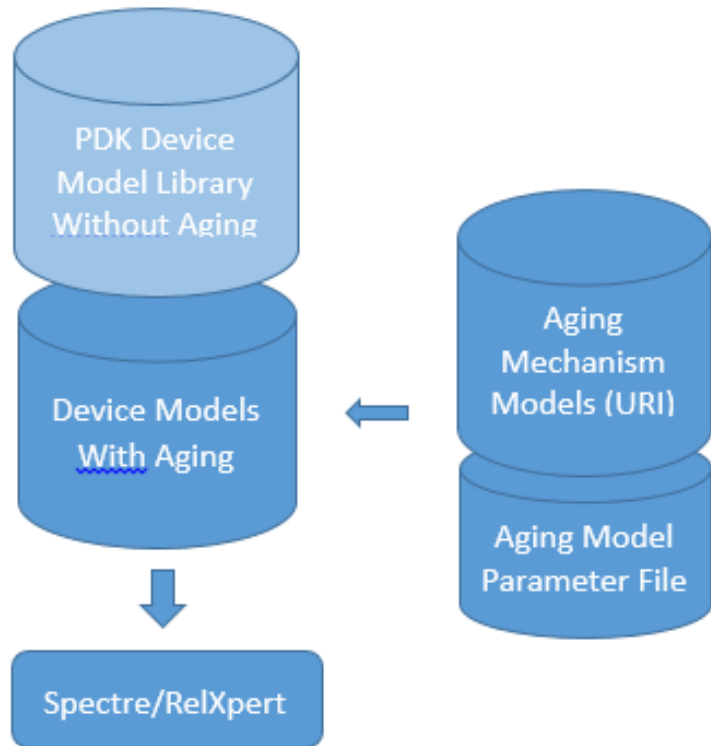


- ▶ Flow is based on BERT methodology (Berkeley Reliability Tools, 1990)
- ▶ Stress is calculated for each device from a transient simulation by use of (built-in or user defined) models describing aging as function of operating point, temperature and time
- ▶ From extrapolation to a specified lifetime, degraded model parameters are calculated and an aged netlist is generated
- ▶ With this netlist, simulation of the “aged” circuit can be performed

- ▶ RelXpert is implemented in Cadence ADE and ADE-(G)XL

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Modular Approach for Aging Model Implementation



- ▶ Direct modifications in PDKs should be avoided (danger of inconsistency if PDK is updated)
- ▶ Models for aging mechanisms to be added optional as external modules
- ▶ Modules should be applicable to different PDKs of different vendors (→ aging model library process independent)
- ▶ Parameterization of the models at vendor data

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Status

- ▶ Aging models available for CMOS/HVMOS; PBTI, NBTI, HCI
- ▶ Aging simulation could explain observed spec violations, especially regarding mismatch
- ▶ Accepted by designers and integrated in design flow (ADE-(G)XL), if supported by PDK vendor

- ▶ Obstacles
 - ▶ Aging data acquisition
 - ▶ Accuracy (e.g. recovery effects not modelled, incomplete consideration of mission profile)
 - ▶ Software Issues
 - Incompatibility (version change)
 - Implementation bugs
 - Incomplete documentation